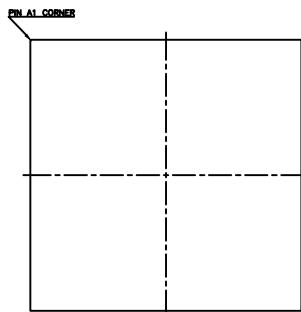
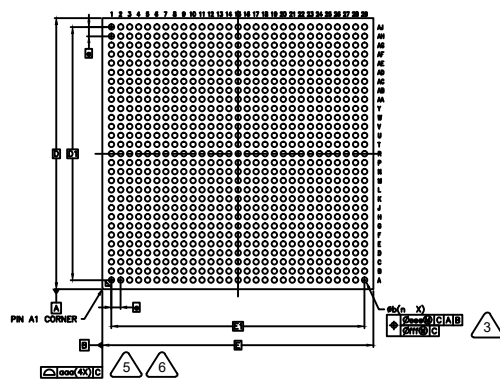
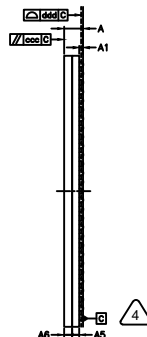


TOP VIEW



SIDE VIEW



BOTTOM VIEW

	Symbol	Common Dimensions		
		MIN.	NOM.	MAX.
Package:		MFC TFBGA		
Body Size:	X	E	15.000	BSC
	Y	D	15.000	BSC
Ball Pitch:	e	0.500		
Total Thickness:	A	0.972	1.048	1.124
Mold Cap Thickness:	A6	0.450		Ref.
Substrate Thickness:	A5	0.388		Ref.
Ball Diameter:		0.300		
Stand Off:	A1	0.160	0.210	0.260
Ball Width:	b	0.250	0.300	0.350
Package Edge Tolerance:	aaa	0.150		
Mold Parallelism:	ccc	0.200		
Coplanarity:	*ddd	0.100		
Ball Offset (Package):	eee	0.150		
Ball Offset (Ball):	fff	0.050		
Ball Count:	n	841		
Edge Ball Center to Center:	X	E1	14.000	
	Y	D1	14.000	

NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. JEDEC REFERENCE: JEP95 DR4.5
- * VALUES ARE BASED ON SUBCON CAPABILITY

Title: Package Outline Drawing	Pkg Type: FCCSP	Document No: POD-240026
Product Family: LAV-AT	Pin Count: 841	
Product Name: LAV-AT-E70-CSG841	Pkg Size: 15x15 mm	
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